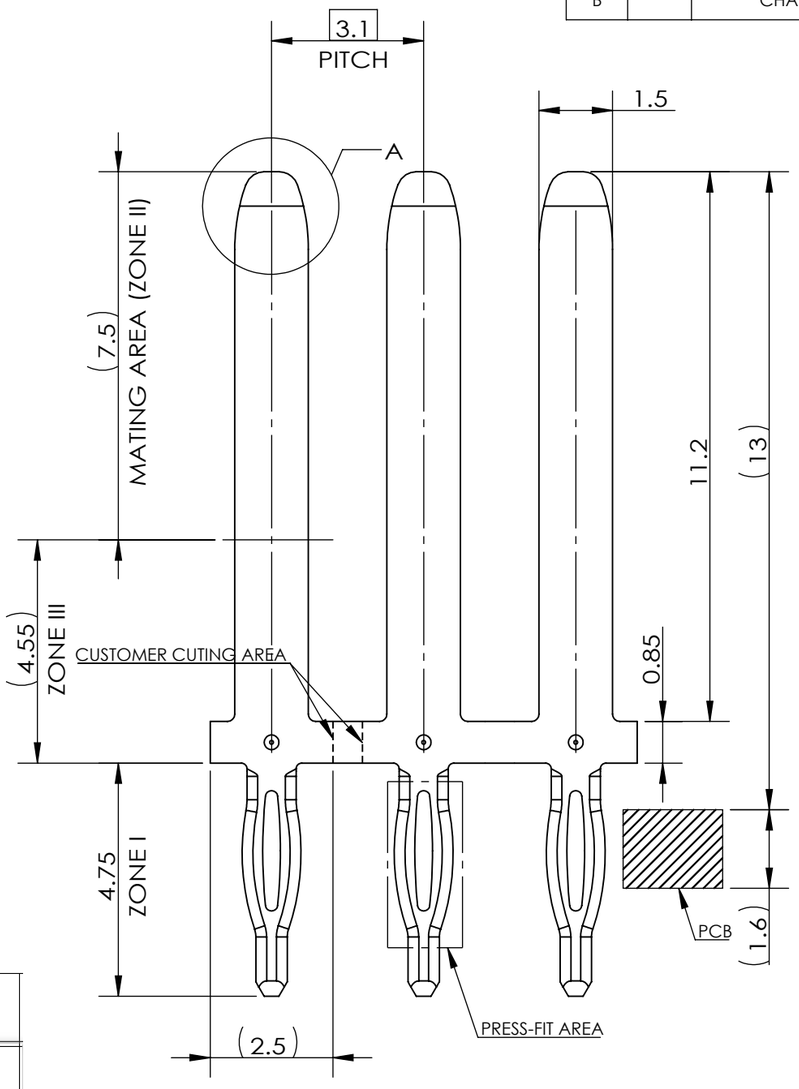
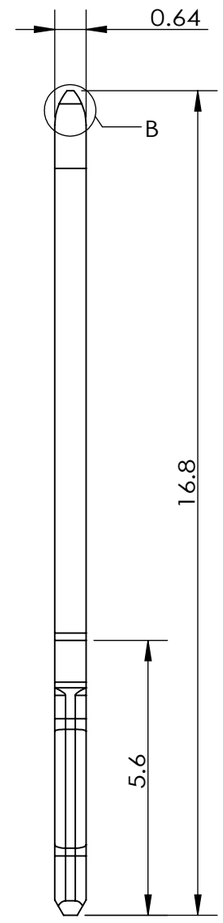
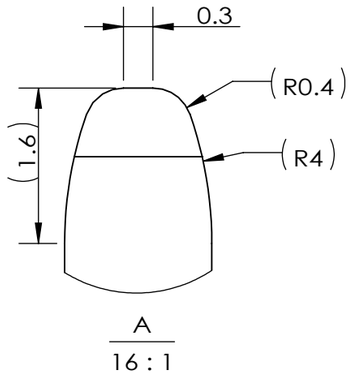
**NOTES (UNLESS OTHERWISE INDICATED):**

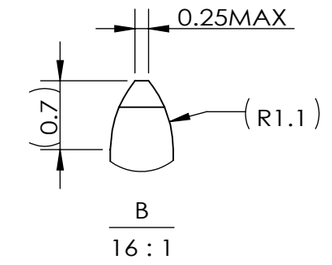
1. MATERIAL: C19010, CuNiSi R580;
2. OPERATION TEMPERATURE: -40~+150α
3. PRESS-FIT AREA
   ENNOVI STANDARD 0.64EON, OPTIONAL 0.64HFEON
4. FINISH SPECIFICATION
   ZONE I (PRESS-FIT AREA): INDICOAT, REFER TO BELOW PLATING TABLE
   ZONE II:0.76~1.5um MATTE Tin, 1.0~2.0um Ni; OR CUSTOMERIZED
   ZONE III:TRANSITION AREA, Ni PLATING, Sn ALLOWED
5. ALL DIMENSIONS AFTER PLATING
6. PCB FINISH: RECOMMENDED ImmSn, OPTIONAL ImAg/OSP
   PCB HOLE CONSTRUCTION: SEE BELOW CHART
7. PRESS FIT DIMENSION REFER TO DRAWING E-MLG03035-APP;
   PRESS FIT PLATING REFER TO DRAWING E-MLG03035-FIN.

| REV. | ZONE | DESCRIPTION | DRAWN BY DD/MM/YYYY | CHECKED BY DD/MM/YYYY | APPROVED BY DD/MM/YYYY | CHANGE NO |
|---|---|---|---|---|---|---|
| A | - | INITIAL RELEASED | Yin LIU 2023-11-29 | - | Sohrab.MORADI 2023-11-29 | - |
| B | | CHANGE TO ENNOVI DRAWING TEMPLATE | Yin LIU 2024-6-28 | | Sohrab.MORADI 2024-6-28 | |



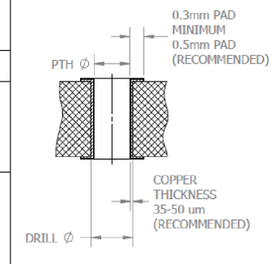

| PART NUMBER | ZONE I PRESS-FIT AREA "TOP PLATE" | ZONE I PRESS-FIT AREA "UNDERPLATE" |
|---|---|---|
| E-MLG03035-FIN-**3** **(INDICOAT)** | **0.3 - 1.1 µm [12 - 45 µin]**<br>• **INDIUM**<br>• POST-PLATED<br>• ELECTRODEPOSITED | **1.0 - 3.0 µm [39 - 120 µin]**<br>• **SULFAMATE NICKEL**<br>• POST-PLATED<br>• ELECTRODEPOSITED |

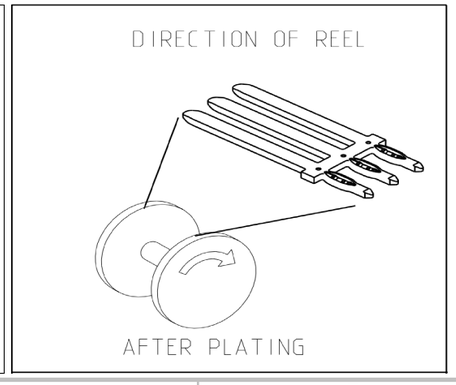
| | | METRIC (mm) |
|---|---|---|
| REQUIRED PCB HOLE CONSTRUCTION | DRILL (USE Ø1.15 METRIC DRILL) | Ø1.150±0.025 |
| | COPPER THICKNESS | 0.050±0.025 |
| | PLATED-THROUGH HOLE (PTH) DIAMETER | Ø1.05 +0.04 -0.05<br>RECOMMENDED: 1.07±0.02 |

CAMPATIBLE PCB HOLE PLATING OPTIONS:
- IMMERSION TIN
- IMMERSION SILVER
- ELECTROLESS NICKEL IMMERSION GOLD (ENIG)
- ORGANIC SOLDERABILITY PRESERVATIVE (OSP)

APPLICABLE FOR NOMINAL PCB THICKNESS 1.5mm OR THICKER

CONSULT PRODUCT ENGINEERING FOR OTHER PCB THICKNESS, PLATING, AND CONSTRUCTION




UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM
FUNDAMENTAL TOLERANCING PRINCIPLE ISO 8015
FOR MISSING DIMENSIONS REFER TO 3D MODEL

GENERAL TOLERANCE: -

MATERIAL: CuNiSi-R580 (C19010-R580)

WEIGHT: -

THIRD ANGLE PROJECTION

SURFACE FINISH: IndiCoat

| | NAME | DATE |
|---|---|---|
| DRAWN | SEE REVISION TABLE | |
| CHECKED | | |
| APPROVED | | |

ENNOVI™



TITLE: 0.64 EON PRESS-FIT 1.5MM BLADE

SCALE: -

DRAWING NO.: IA6522

SIZE: A3

DESCRIPTION: -

SHEET 1 / 1

NOTES (UNLESS OTHERWISE SPECIFIED):

1. MATERIAL:
   - COPPER ALLOY; SEE CHART FOR OPTIONS
2. EYE FINISH:
   - POST-PLATED PER DRAWING E-MLG03035-FIN
3. PCB HOLE REQUIREMENTS:
   - SEE REQUIRED PCB HOLE CONSTRUCTION CHART

4. MAX TEMP. RATING IS TEMPERATURE AT WHICH MATERIAL BEGINS TO STRESS RELAX. THE PCB GLASS TRANSITION TEMPERATURE RATING (Tg) MUST ALSO BE 20°C HIGHER THAN MAX APPLICATION TEMPERATURE FOR PROPER INTERFACE PERFORMANCE.

5. DIMENSIONS AND GEOMETRIES SHOWN ARE SYMBOLIC REPRESENTATIONS ONLY.

6. CONSULT PRODUCT ENGINEERING FOR POSSIBLE DIMENSIONAL CHANGES.

AVAILABLE ALLOYS

| TYPE | % IACS | MAX. TEMP. RATING 4. |
|---|---|---|
| PHOSPHOR BRONZE | 13-18 | 125°C |
| HI-PERFORMANCE ALLOY | 50 | 175°C |
| HI-CONDUCTIVITY ALLOY | 75-80 | 200°C |

REVISIONS

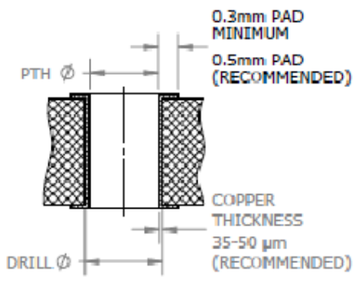
| REV. | DESCRIPTION | DATE | APPROVED |
|---|---|---|---|
| A | INITIAL RELEASE | 9/14/2007 | RLS |
| B | UPDATE | 2/29/2008 | RLS |
| C | ADDED PCB HOLE CONSTRUCTION SKETCH | 4/6/2009 | JDP |
| D | UPDATED AVAILABLE ALLOYS CHART | 10/16/2009 | JDP |
| E | UPDATED DRAWING VIEWS AND NOTES | 12/05/2013 | JDP |
| F | UPDATED ALLOY CHART, PRESS-FIT LGTH & ADD TOL. | 06/20/2016 | YF |
| G | UPDATED PCB HOLE CONSTRUCTION CHART NOTE | 06/21/2016 | YF |
| H | UPD. PCB HOLE CONSTRUCT. CHART, DIM., NOTES | 04/18/2018 | YF |
| J | UPD. DIM SCHEME, ADD NOTE#5 & #6, UPD. VIEWS & NOTES | 10/30/2020 | YF |

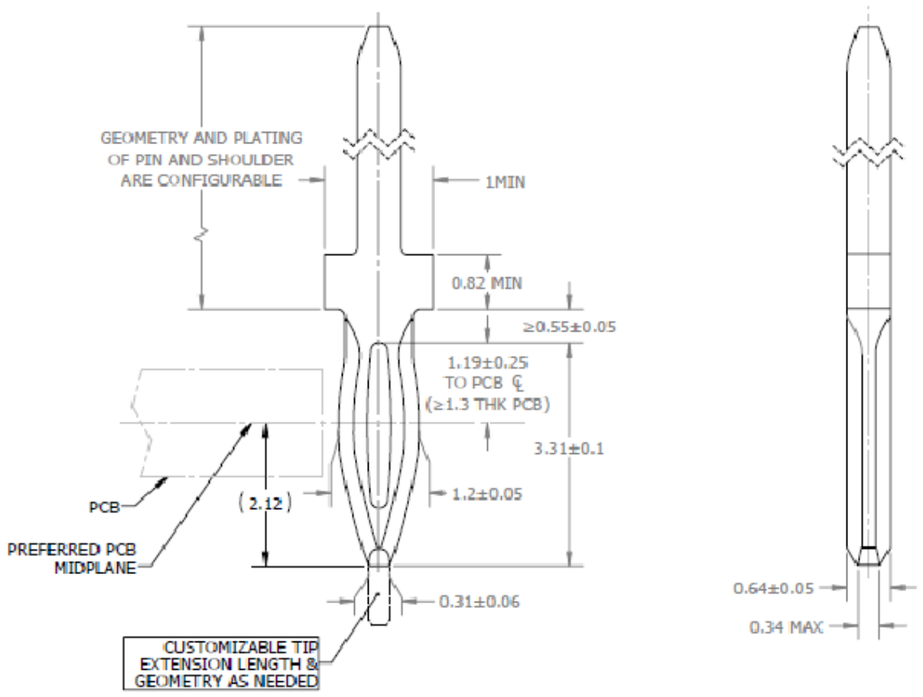
| | | METRIC (mm) |
|---|---|---|
| REQUIRED PCB HOLE CONSTRUCTION | DRILL (USE Ø1.15 METRIC DRILL) | Ø1.150±0.025 |
| | COPPER THICKNESS | 0.050±0.025 |
| | PLATED-THROUGH HOLE (PTH) DIAMETER | Ø1.05 +0.04 -0.05 |

COMPATIBLE PCB HOLE PLATING OPTIONS:
- IMMERSION TIN
- IMMERSION SILVER
- ELECTROLESS NICKEL IMMERSION GOLD (ENIG)
- ORGANIC SOLDERABILITY PRESERVATIVE (OSP)

APPLICABLE FOR NOMINAL PCB THICKNESS 1.0mm OR THICKER.

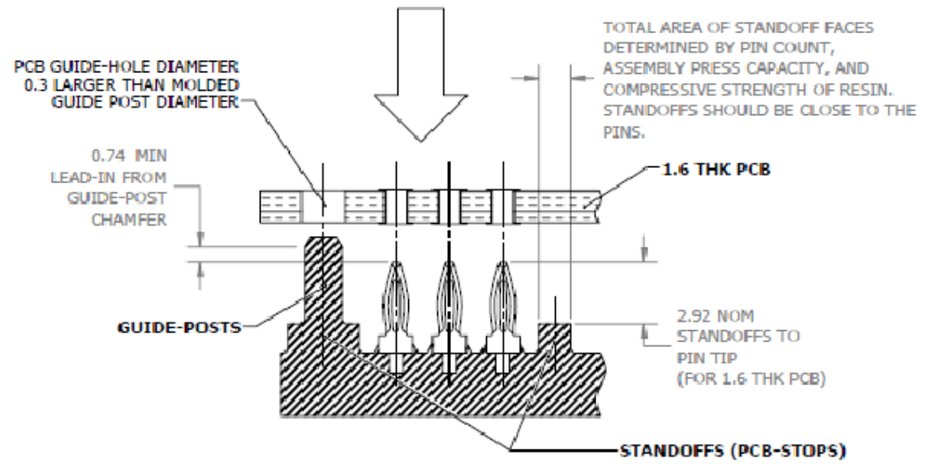
CONSULT PRODUCT ENGINEERING FOR OTHER PCB THICKNESS, PLATING, AND CONSTRUCTION



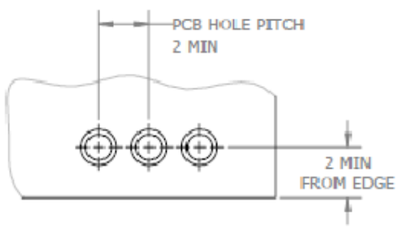




## SUGGESTED APPLICATION DESIGN PRACTICES

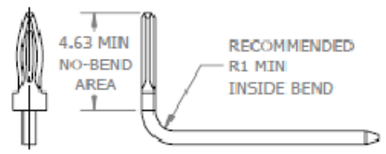
THE PUSH TOOL USED TO PRESS THE PCB ONTO THE PINS SHOULD ENGAGE ONLY THE BOARD LAMINATE (NOT TRACES) AND ENGAGE CLOSE TO THE PINS AS WELL AS DIRECTLY OVER EACH STANDOFF SURFACE




**OVERMOLDED HOUSING WITH PRESS-FITS**




**PCB HOLE LOCATIONS**




**RIGHT ANGLE PIN**



UNLESS OTHERWISE SPECIFIED: UNITS: mm
MATERIAL: SEE NOTES
FINISH: SEE NOTES
DO NOT SCALE DRAWING

| | NAME | DATE |
|---|---|---|
| DRAWN | Y.FUKUDA | 10OCT2020 |
| CHECKED | C.TORIGIAN | 10OCT2020 |

Interplex

P/N: 064_EON_105

TITLE: 0.64 EON PRESS-FIT APPLICATION

SIZE C | DWG. NO. E-MLG03035-APP | REV J

SHEET 1 OF 1